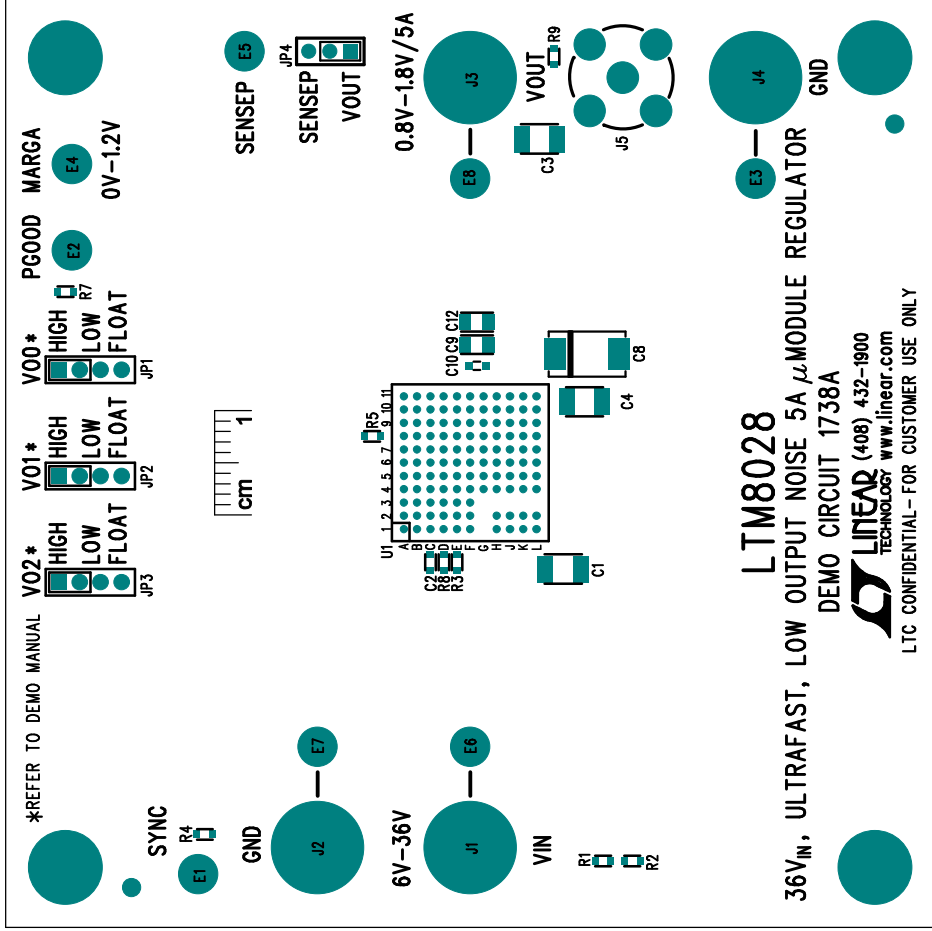
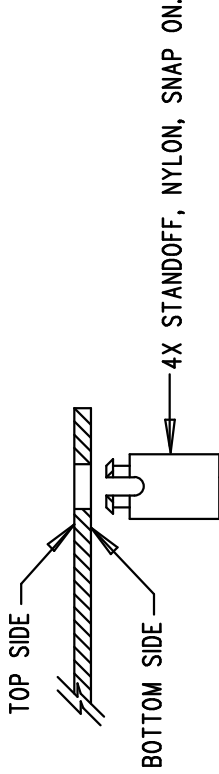


REVISION HISTORY			
ECO	REV	DESCRIPTION	APP. ENG.
-	2	PRODUCTION	JAINO P.
			DATE
			05-07-12

## NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
5. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
6. MAXIMUM SOLDER TEMPERATURE IS 240° C
7. INSTALL 4 STANDOFFS AT 4 LOCATIONS AS SHOWN BELOW:



APPROVALS		LINEAR TECHNOLOGY		1630 MCCARTHY BLVD MILPITAS, CA 95035 PH: (408)432-1900 www.linear.com LTC CONFIDENTIAL - FOR CUSTOMER USE ONLY	
PCB DES.	JW	TITLE: TOP ASSEMBLY DRAWING			
APP ENG.	JAINO P.	36Vin, ULTRAFAST, LOW OUTPUT NOISE 5A $\mu$ MODULE REGULATOR			
		SIZE	IC NO.	LTM8028EY	REV.
		N/A		DEMO CIRCUIT 1738A	2
SCALE = NONE		FILENAME: 1738A-2.PCB		SHT 1 OF 2	